

LOW VOLTAGE CMOS DUAL D-TYPE FLIP FLOP WITH PRESET AND CLEAR (5V TOLERANT INPUTS)

- HIGH SPEED: f_{MAX} = 145MHz (TYP.) at V_{CC} = 3.3V
- 5V TOLERANT INPUTS
- INPUT VOLTAGE LEVEL: V_{IL}=0.8V, V_{IH}=2V AT V_{CC}=3V
- LOW POWER DISSIPATION: $I_{CC} = 2 \mu A \text{ (MAX.)}$ at $T_A=25 ^{\circ}\text{C}$
- LOW NOISE: $V_{OLP} = 0.3V$ (TYP.) at $V_{CC} = 3.3V$
- SYMMETRICAL OUTPUT IMPEDANCE: |I_{OH}| = I_{OL} = 4mA (MIN)
- BALANCED PROPAGATION DELAYS: tplh ≅ tphl
- OPERATING VOLTAGE RANGE:
 V_{CC}(OPR) = 2V to 3.6V (1.2V Data Retention)
- PIN AND FUNCTION COMPATIBLE WITH 74 SERIES 74
- IMPROVED LATCH-UP IMMUNITY
- POWER DOWN PROTECTION ON INPUTS

DESCRIPTION

The 74LVX74 is a low voltage CMOS DUAL D-TYPE FLIP-FLOP WITH PRESET AND CLEAR NON INVERTING fabricated with sub-micron silicon gate and double-layer metal wiring C²MOS technology. It is ideal for low power, battery operated and low noise 3.3V applications.

SOP TSSOP

Table 1: Order Codes

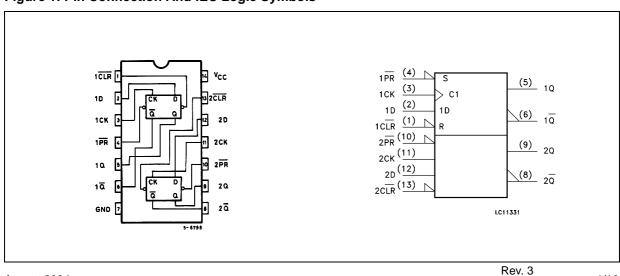
PACKAGE	T & R				
SOP	74LVX74MTR				
TSSOP	74LVX74TTR				

A signal on the D INPUT is transferred to the Q OUTPUT during the positive going transition of the clock pulse. CLR and PR are independent of the clock and accomplished by a low setting on the appropriate input.

Power down protection is provided on all inputs and 0 to 7V can be accepted on inputs with no regard to the supply voltage.

This device can be used to interface 5V to 3V system. It combines high speed performance with the true CMOS low power consumption. All inputs and outputs are equipped with protection circuits against static discharge, giving them 2KV ESD immunity and transient excess voltage.

Figure 1: Pin Connection And IEC Logic Symbols



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Figure 2: Input Equivalent Circuit

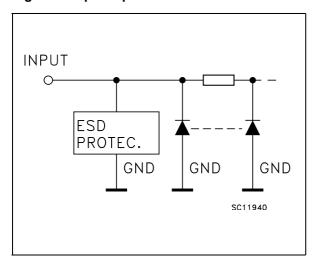


Table 2: Pin Description

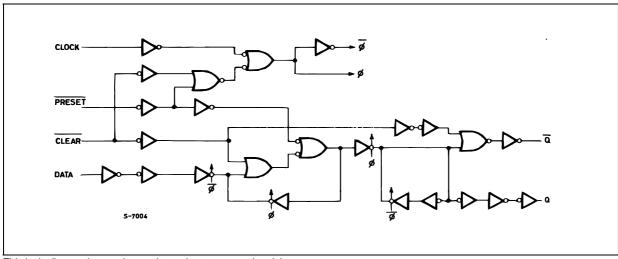
PIN N°	SYMBOL	NAME AND FUNCTION
1, 13	1CLR, 2CLR	Asynchronous Reset - Direct Input
2, 12	1D, 2D	Data Inputs
3, 11	1CK, 2CK	Clock Input (LOW to HIGH, Edge Triggered)
4, 10	1PR, 2PR	Asynchronous Set - Direct Input
5, 9	1Q, 2Q	True Flip-Flop Outputs
6, 8	1Q, 2Q	Complement Flip-Flop Outputs
7	GND	Ground (0V)
14	V _{CC}	Positive Supply Voltage

Table 3: Truth Table

	INP	JTS		OUT	PUTS	FUNCTION
CLR	PR	D	СК	Q	Q	FUNCTION
L	Н	X	Х	L	Н	CLEAR
Н	L	Х	Х	Н	L	PRESET
L	L	Х	Х	Н	Н	
Н	Н	L		L	Н	
Н	Н	Н		Н	L	
Н	Н	Х	Z	Q _n	Q _n	NO CHANGE

X : Don't Care

Figure 3: Logic Diagram



This logic diagram has not be used to estimate propagation delays

Table 4: Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _{CC}	Supply Voltage	-0.5 to +7.0	V
V _I	DC Input Voltage	-0.5 to +7.0	V
Vo	DC Output Voltage	-0.5 to V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current	- 20	mA
I _{OK}	DC Output Diode Current	± 20	mA
Io	DC Output Current	± 25	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current	± 50	mA
T _{stg}	Storage Temperature	-65 to +150	°C
TL	Lead Temperature (10 sec)	300	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied.

Table 5: Recommended Operating Conditions

Symbol	Parameter	Value	Unit
V _{CC}	Supply Voltage (note 1)	2 to 3.6	V
V _I	Input Voltage	0 to 5.5	V
V _O	Output Voltage	0 to V _{CC}	V
T _{op}	Operating Temperature	-55 to 125	°C
dt/dv	Input Rise and Fall Time (note 2) (V _{CC} = 3.3V)	0 to 100	ns/V

¹⁾ Truth Table guaranteed: 1.2V to 3.6V 2) $V_{\mbox{\footnotesize{IN}}}$ from 0.8V to 2.0V

Table 6: DC Specifications

		Т	est Condition				Value				
Symbol	Parameter	v _{cc}		Т	T _A = 25°C			85°C	-55 to 125°C		Unit
		(V)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
V _{IH}	High Level Input	2.0		1.5			1.5		1.5		
	Voltage	3.0		2.0			2.0		2.0		V
		3.6		2.4			2.4		2.4		
V_{IL}	Low Level Input	2.0				0.5		0.5		0.5	
	Voltage	3.0				0.8		0.8		0.8	V
		3.6				0.8		0.8		0.8	
V _{OH}	High Level Output	2.0	I _O =-50 μA	1.9	2.0		1.9		1.9		
	Voltage	3.0	I _O =-50 μA	2.9	3.0		2.9		2.9		V
		3.0	I _O =-4 mA	2.58			2.48		2.4		
V _{OL}	Low Level Output	2.0	I _O =50 μA		0.0	0.1		0.1		0.1	
	Voltage	3.0	I _O =50 μA		0.0	0.1		0.1		0.1	V
		3.0	I _O =4 mA			0.36		0.44		0.55	
I _I	Input Leakage Current	3.6	V _I = 5V or GND			± 0.1		± 1		± 1	μΑ
I _{CC}	Quiescent Supply Current	3.6	$V_I = V_{CC}$ or GND			2		20		20	μΑ



Table 7: Dynamic Switching Characteristics

		Test Condition		Value								
Symbol	Parameter	V _{CC} (V)		T _A = 25°C			-40 to 85°C		-55 to 125°C		Unit	
				Min.	Тур.	Max.	Min.	Max.	Min.	Max.		
V _{OLP}	Dynamic Low Voltage			3.3 C _L = 50 pF		0.3	0.5					
V _{OLV}	Quiet Output (note 1, 2)	3.3	-0.5		-0.3							
V _{IHD}	Dynamic High Voltage Input (note 1, 3)	3.3	2								V	
V _{ILD}	Dynamic Low Voltage Input (note 1, 3)	3.3				0.8						

¹⁾ Worst case package.

Table 8: AC Electrical Characteristics (Input $t_r = t_f = 3ns$)

		Te	st Con	dition				Value				
Symbol	Parameter	v _{cc}	CL		Т	A = 25°	С	-40 to	85°C	-55 to	125°C	Unit
		(V)	(pF)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
t _{PLH} t _{PHL}	Propagation Delay Time CK to Q or Q	2.7	15			7.3	15.0	1.0	18.5	1.0	18.5	
		2.7	50			9.8	18.5	1.0	22.0	1.0	22.0	
		3.3 ^(*)	15			5.7	9.7	1.0	11.5	1.0	11.5	ns
		3.3 ^(*)	50			8.2	13.2	1.0	15.0	1.0	15.0	
t _{PLH} t _{PHL}	Propagation Delay Time	2.7	15			8.4	15.6	1.0	18.5	1.0	18.5	
	PR or CLR to Q or Q	2.7	50			10.9	19.1	1.0	22.0	1.0	22.0	
		3.3 ^(*)	15			6.6	10.1	1.0	12.0	1.0	12.0	ns
		3.3 ^(*)	50			9.1	13.6	1.0	15.5	1.0	15.5	
t _w	t _w Minimum Pulse Width HIGH or LOW, CK	2.7	50				8.5		10.0		10.0	
		3.3 ^(*)	50				6.0		7.0		7.0	ns
t _{w(L)}	Minimum Pulse Width	2.7	50				8.5		10.0		10.0	
	LOW PR or CLR	3.3 ^(*)	50				6.0		7.0		7.0	ns
t _s	Minimum Setup Time D	2.7	50				8.0		9.5		9.5	
	to CK HIGH or LOW	3.3 ^(*)	50				5.5		6.5		6.5	ns
t _h	Minimum Hold Time D	2.7	50				0.5		0.5		0.5	
	to CK HIGH or LOW	3.3 ^(*)	50				0.5		0.5		0.5	ns
t _{REM}	Minimum Removal Time	2.7	50				6.5		7.5		7.5	
	PR or CLR to CK	3.3 ^(*)	50				5.0		5.0		5.0	ns
f _{MAX}	Maximum Clock	2.7	15		55	135		50		50		
	Frequency	2.7	50		45	60		40		40		
		3.3 ^(*)	15		95	145		80		80		MHz
		3.3 ^(*)	50		60	85		50		50		
t _{OSLH}	Output To Output Skew	2.7	50			0.5	1.0		1.5		1.5	
toshl	Time (note1, 2)	3.3(*)	50			0.5	1.0		1.5		1.5	ns

¹⁾ Skew is defined as the absolute value of the difference between the actual propagation delay for any two outputs of the same device switching in the same direction, either HIGH or LOW
2) Parameter guaranteed by design
(*) Voltage range is 3.3V ± 0.3V

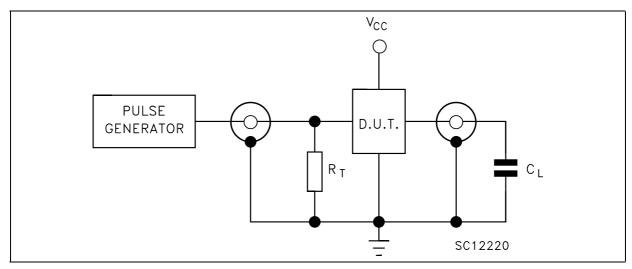
²⁾ Max number of outputs defined as (n). Data inputs are driven 0V to 3.3V, (n-1) outputs switching and one output at GND. 3) Max number of data inputs (n) switching. (n-1) switching 0V to 3.3V. Inputs under test switching: 3.3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}), f=1MHz.

Table 9: Capacitive Characteristics

	Parameter	Test Condition		Value							
Symbol		V _{CC} (V)		T _A = 25°C			-40 to 85°C		-55 to 125°C		Unit
				Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
C _{IN}	Input Capacitance	3.3			4	10		10		10	pF
C _{PD}	Power Dissipation Capacitance (note 1)	3.3	f _{IN} = 10 MHz		25						pF

¹⁾ C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation. $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}/2$ (per circuit)

Figure 4: Test Circuit



 C_L =15/50pF or equivalent (includes jig and probe capacitance) R_T = Z_{OUT} of pulse generator (typically 50 $\!\Omega)$

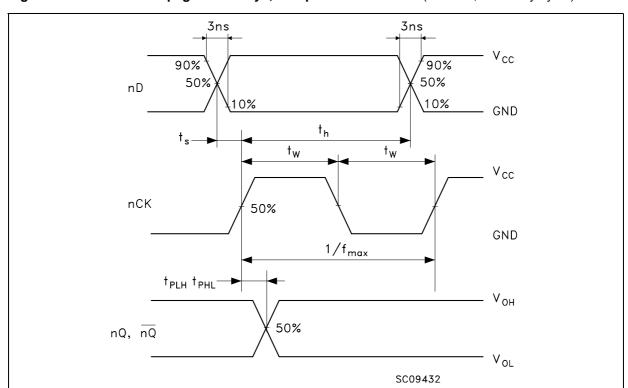
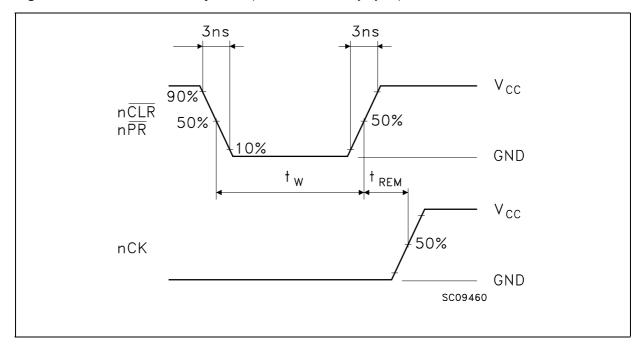


Figure 5: Waveform - Propagation Delays, Setup And Hold Times (f=1MHz; 50% duty cycle)

Figure 6: Waveform - Recovery Time (f=1MHz; 50% duty cycle)



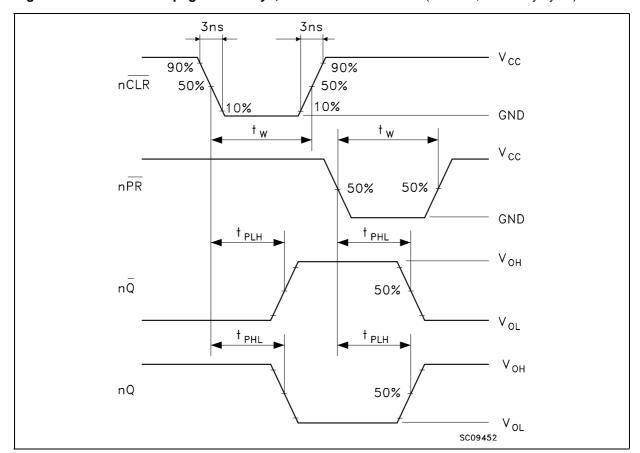
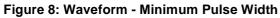
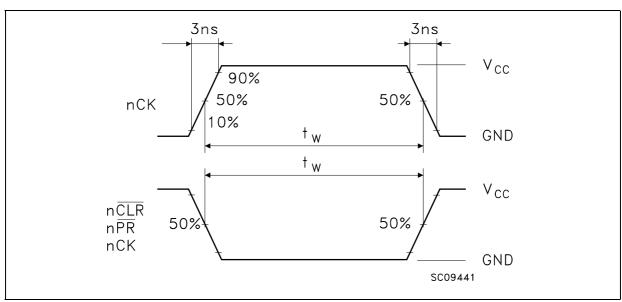


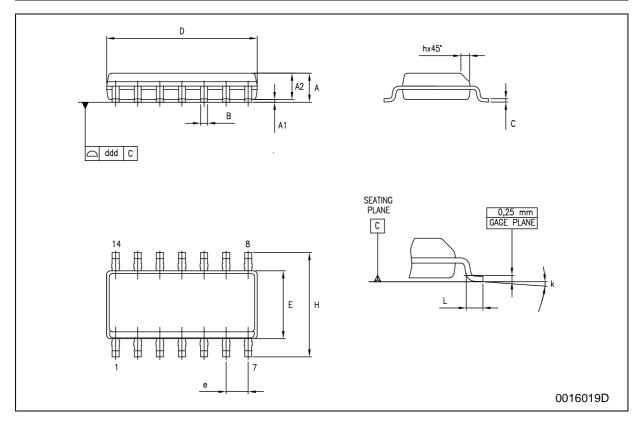
Figure 7: Waveform - Propagation Delays, Minimum Pulse Width (f=1MHz; 50% duty cycle)





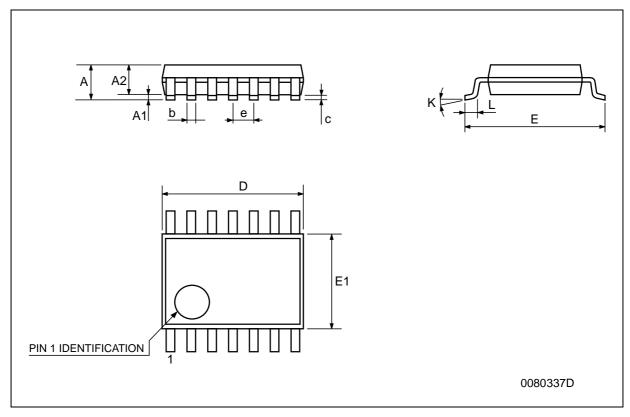
SO-14 MECHANICAL DATA

DIM.		mm.			inch	
DIN.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
А	1.35		1.75	0.053		0.069
A1	0.1		0.25	0.004		0.010
A2	1.10		1.65	0.043		0.065
В	0.33		0.51	0.013		0.020
С	0.19		0.25	0.007		0.010
D	8.55		8.75	0.337		0.344
Е	3.8		4.0	0.150		0.157
е		1.27			0.050	
Н	5.8		6.2	0.228		0.244
h	0.25		0.50	0.010		0.020
L	0.4		1.27	0.016		0.050
k	0°		8°	0°		8°
ddd			0.100			0.004

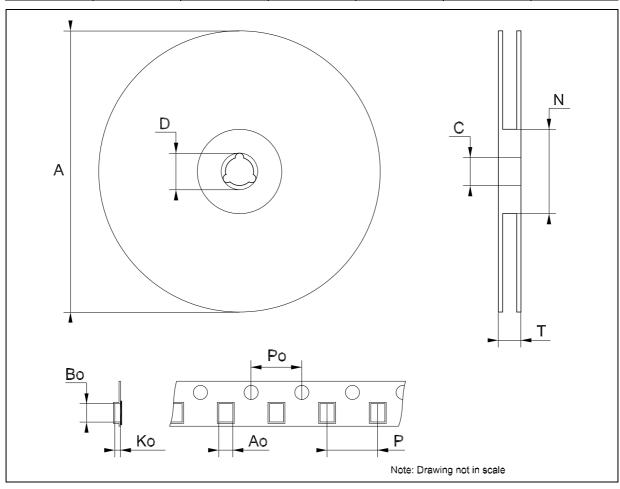


TSSOP14 MECHANICAL DATA

DIM.		mm.		inch				
DIWI.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.		
А			1.2			0.047		
A1	0.05		0.15	0.002	0.004	0.006		
A2	0.8	1	1.05	0.031	0.039	0.041		
b	0.19		0.30	0.007		0.012		
С	0.09		0.20	0.004		0.0089		
D	4.9	5	5.1	0.193	0.197	0.201		
E	6.2	6.4	6.6	0.244	0.252	0.260		
E1	4.3	4.4	4.48	0.169	0.173	0.176		
е		0.65 BSC			0.0256 BSC			
К	0°		8°	0°		8°		
L	0.45	0.60	0.75	0.018	0.024	0.030		

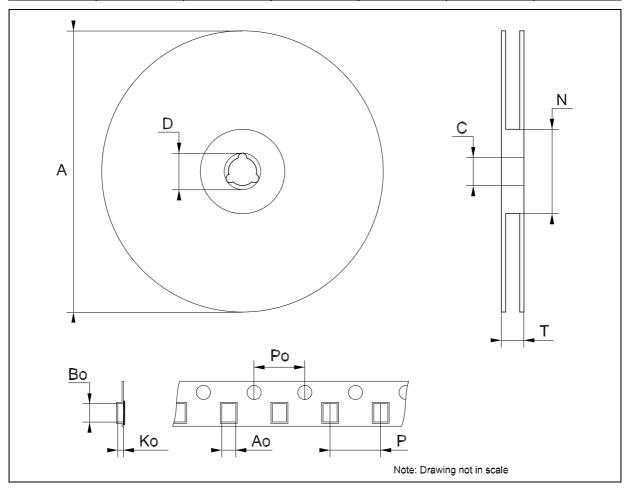


DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
А			330			12.992
С	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
Т			22.4			0.882
Ao	6.4		6.6	0.252		0.260
Во	9		9.2	0.354		0.362
Ko	2.1		2.3	0.082		0.090
Ро	3.9		4.1	0.153		0.161
Р	7.9		8.1	0.311		0.319



Tape & Reel TSSOP14 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
Α			330			12.992
С	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
Т			22.4			0.882
Ao	6.7		6.9	0.264		0.272
Во	5.3		5.5	0.209		0.217
Ko	1.6		1.8	0.063		0.071
Ро	3.9		4.1	0.153		0.161
Р	7.9		8.1	0.311		0.319



74LVX74

Table 10: Revision History

Date	Revision	Description of Changes
27-Aug-2004	3	Ordering Codes Revision - pag. 1.

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